

U.S. Department of Commerce, Patent and Trademark Office		Atty Docket No.	Serial No.
		M-12589 US	10/080,468
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Applicant(s)	
(Use several sheets if necessary)		Hua Ji	
		Filing Date	Group
		February 22, 2002	Unknown

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
A. M	AA	5,872,058	02/16/99	Van Cleemput et al.	438	692	
	AB	6,030,881	02/29/00	Papasouliotis et al.	438	424	
	AC	6,136,685	10/24/00	Narwankar et al.	438	624	
	AD	6,211,040 B1	04/03/01	Liu et al.	438	424	
	AE						
	AF						
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	AH						
	AI						
	AJ						
	AK						

Foreign Patent Documents

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Translation

		Document	Date	Country	Class	Subclass	Yes	No
	AI							
	AM							
	AN							
	AO							
	AP							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

A. M	AQ	Schravendijk, et al., "Dielectric Gap Fill Technology for STI for the 0.10 μm Era", Novellus Systems, Inc., 6 pages
A. M	AR	Conti, et al., "Processing Methods to Fill High Aspect Ratio Gaps Without Premature Constriction," DUMIC Conference 1999, pages 201-209
	AS	

Examiner ANH D. Mai Date Considered 11/14/02

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.